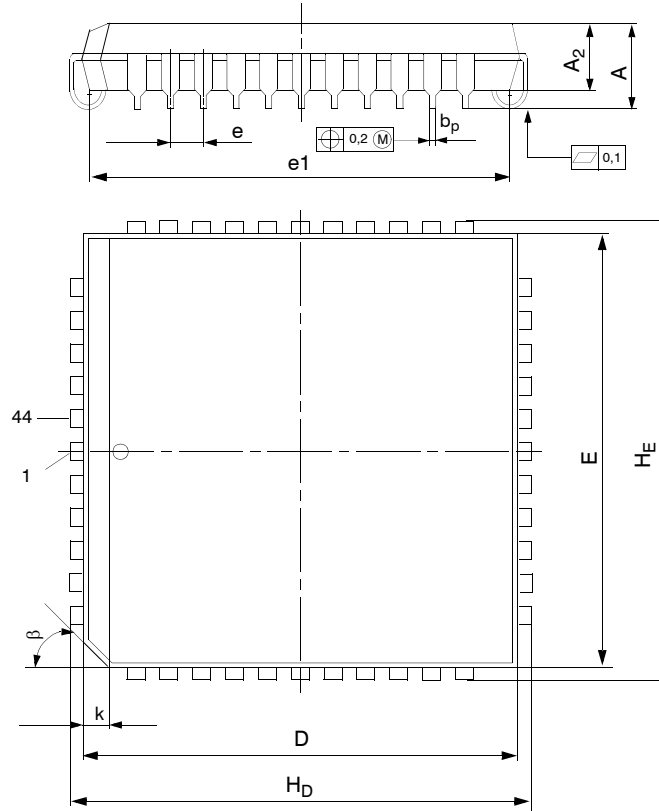


Dimensions in millimetres

Based on IEC 191-2Q: Type 112E10

1 Dimensions



Dimensions of Sub-Group B1	
A_{max}	4,60
b_{Pmin}	0,33
b_{Pmax}	0,53
e_{nom}	1,27
H_{Dmin}	17,40
H_{Dmax}	17,65
H_{Emin}	17,40
H_{Emax}	17,65

2 Weight $\leq 2,4$ g

3 Package Body Material Low Stress Epoxy

4 Lead Material FeNi-Alloy or Cu-Alloy

5 Lead Finish solder plating

6 Lead Form J-bends

Dimensions of Sub-Group C1	
A_{min}	4,15
A_{2min}	3,10
A_{2max}	3,96
D_{min}^*	16,50
D_{max}^*	16,70
E_{min}^*	16,50
E_{max}^*	16,70
k_{min}	1,00
β	45°
e_{1min}	15,00
e_{1max}	16,00

* without mold-flash

Zentrum Mikroelektronik Dresden AG		
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